NB7V58M

1.8 V / 2.5 V / 3.3 V Differential 2:1 Clock / Data Multiplexer / Translator with CML Outputs

Multi−Level Inputs w/ Internal Termination

Description

The NB7V58M is a high performance differential 2−to−1 Clock or Data multiplexer. The differential inputs incorporate internal 50 Ω termination resistors that are accessed through the VT pin. This feature allows the NB7V58M to accept various logic level standards, such as LVPECL, CML or LVDS.

The NB7V58M produces minimal Clock or Data jitter operating up to 7 GHz or 10.7 Gb/s, respectively. As such, the NB7V58M is ideal for SONET, GigE, Fiber Channel, Backplane and other Clock/Data distribution applications.

The 16 mA differential CML outputs provide matching internal 50 Ω terminations and 400 mV output swings when externally terminated with a 50 Ω resistor to V_{CC}.

The NB7V58M is offered in a low profile 3 mm x 3 mm 16−pin QFN package and is a member of the GigaComm™ family of high performance Clock / Data products. For applications that require equalization, the pin−compatible NB7VQ58M is also available. Application notes, models, and support documentation are available at www.onsemi.com.

Features

- Maximum Input Data Rate > 10.7 Gb/s
- Data Dependent Jitter < 10 ps
- Maximum Input Clock Frequency > 7 GHz
- Random Clock Jitter < 0.8 ps RMS
- 180 ps Typical Propagation Delay
- 35 ps Typical Rise and Fall Times
- Differential CML Outputs, 400 mV Peak−to−Peak, Typical
- Operating Range: V_{CC} = 1.71 V to 3.6 V with GND = 0 V
- Internal 50 Ω Input Termination Resistors
- QFN−16 Package, 3 mm x 3 mm
- −40°C to +85°C Ambient Operating Temperature
- This is a Pb−Free Device

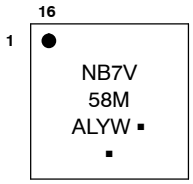
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MARKING DIAGRAM*



QFN−16
MN SUFFIX
CASE 485G

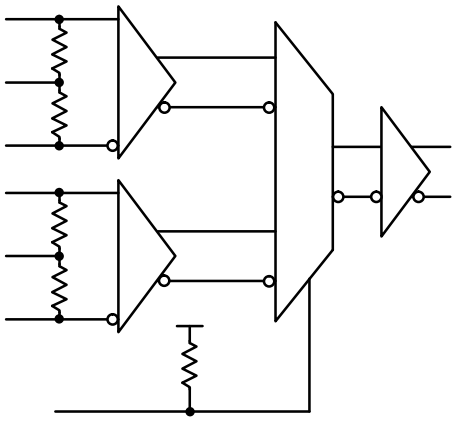


A	= Assembly Location
L	= Wafer Lot
Y	= Year
W	= Work Week
▪	= Pb−Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

SIMPLIFIED BLOCK DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

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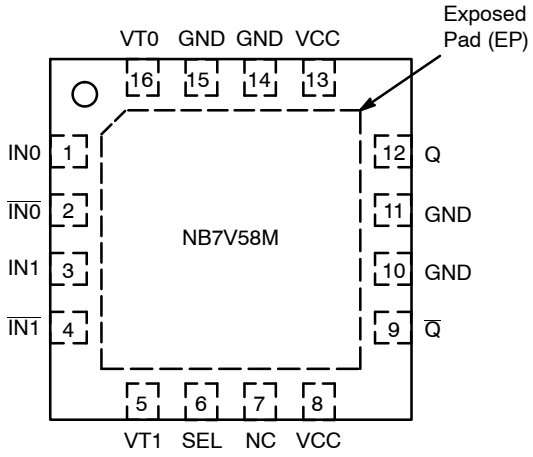


Figure 1. Pin Configuration (Top View)

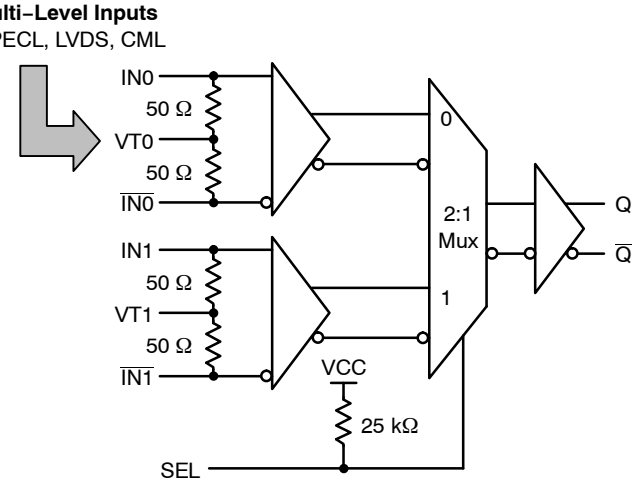


Figure 2. Detailed Block Diagram

Table 1. SELect FUNCTION TRUTH TABLE

SEL	Q	$\overline{Q}$
L	IN0	$\overline{IN0}$
H	IN1	$\overline{IN1}$

Table 2. PIN DESCRIPTION

Pin	Name	I/O	Description
1	IN0	LVPECL, CML, LVDS Input	Noninverted Differential Input (Note 1)
2	$\overline{IN0}$	LVPECL, CML, LVDS Input	Inverted Differential Input (Note 1)
3	IN1	LVPECL, CML, LVDS Input	Noninverted Differential Input (Note 1)
4	$\overline{IN1}$	LVPECL, CML, LVDS Input	Inverted Differential Input (Note 1)
5	VT1	–	Internal 50 Ω Termination Pin for IN1/$\overline{IN1}$
6	SEL	LVTTL/LVCMOS Input	SEL Input. Low for IN0 inputs, high for IN1 inputs. (Note 1) Pin will default HIGH when left open (has internal pull−up resistor)
7	NC		No Connect
8	VCC	–	Positive Supply Voltage (Note 2)
9	$\overline{Q}$	CML Output	Inverted Differential Output
10	GND	–	Negative Supply Voltage
11	GND	–	Negative Supply Voltage
12	Q	CML Output	Noninverted Differential Output
13	VCC	–	Positive Supply Voltage (Note 2)
14	GND	–	Negative Supply Voltage
15	GND	–	Negative Supply Voltage
16	VT0	–	Internal 50 Ω Termination Pin for IN0/$\overline{IN0}$
–	EP	–	The Exposed Pad (EP) on the QFN−16 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat−sinking conduit. The pad is electrically connected to the die, and must be electrically and thermally connected to GND on the PC board.

1. In the differential configuration when the input termination pins (VT0, VT1) are connected to a common termination voltage or left open, and if no signal is applied on IN0/$\overline{IN0}$, IN1/$\overline{IN1}$ inputs, then the device will be susceptible to self−oscillation. Q/$\overline{Q}$ outputs have internal 50 Ω source termination resistors.
2. All VCC and GND pins must be externally connected to a power supply for proper operation.

Table 3. ATTRIBUTES

Characteristics		Value
ESD Protection	Human Body Model Machine Model	> 2 kV > 200 V
R_{PU} – SEL Input Pull−up Resistor		25 kΩ
Moisture Sensitivity (Note 3)	QFN−16	Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in
Transistor Count		312
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test		

3. For additional information, see Application Note AND8003/D.

Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	Positive Power Supply	GND = 0 V		4.0	V
V_{IN}	Positive Input Voltage	GND = 0 V		−0.5 to V_{CC} +0.5	V
V_{INPP}	Differential Input Voltage |INn − $\overline{INn}$|			1.89	V
I_{OUT}	Output Current	Continuous Surge		34 40	mA
I_{IN}	Input Current Through R_T (50 Ω Resistor)			±40	mA
T_A	Operating Temperature Range			−40 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction−to−Ambient) (Note 4)	0 LFPM 500 LFPM	QFN−16 QFN−16	42 35	°C/W
θ_{JC}	Thermal Resistance (Junction−to−Case) (Note 4)		QFN−16	4	°C/W
T_{sol}	Wave Solder Pb−Free			265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

4. JEDEC standard multilayer board − 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 5. DC CHARACTERISTICS POSITIVE CML OUTPUT (V_{CC} = 1.71 V to 3.6 V; GND = 0 V; T_A = −40°C to 85°C) (Note 5)

Symbol	Characteristic	Min	Typ	Max	Unit
POWER SUPPLY CURRENT					
I_{CC}	Power Supply Current (Inputs and Outputs Open)		100	150	mA
CML OUTPUTS (Note 6)					
V_{OH}	Output HIGH Voltage VCC = 3.3 V VCC = 2.5 V VCC = 1.8 V	V_{CC} − 30 3270 2470 1770	V_{CC} − 5 3295 2495 1795	V_{CC} 3300 2500 1800	mV
V_{OL}	Output LOW Voltage VCC = 3.3 V VCC = 2.5 V VCC = 1.8 V	V_{CC} − 500 2800 2000 1300	V_{CC} − 400 2900 2100 1400	V_{CC} − 300 3000 2200 1500	mV
DIFFERENTIAL INPUTS DRIVEN SINGLE−ENDED (Note 7) (Figures 6 & 8)					
V_{th}	Input Threshold Reference Voltage Range (Note 8)	1050		V_{CC} − 100	mV
V_{IH}	Single−ended Input HIGH Voltage	V_{th} + 100		V_{CC}	mV
V_{IL}	Single−ended Input LOW Voltage	GND		V_{th} − 100	mV
V_{ISE}	Single−ended Input Voltage (V_{IH} − V_{IL})	200		1200	mV
DIFFERENTIAL IN0/$\overline{\text{IN0}}$, IN1/$\overline{\text{IN1}}$, INPUTS DRIVEN DIFFERENTIALLY (Figures 6 & 9) (Note 9)					
V_{IHD}	Differential Input HIGH Voltage	1100		V_{CC}	mV
V_{ILD}	Differential Input LOW Voltage	GND		V_{CC} − 100	mV
V_{ID}	Differential Input Voltage (V_{IHD} − V_{ILD})	100		1200	mV
V_{CMR}	Input Common Mode Range (Differential Configuration, Note 10) (Figure 10)	1050		V_{CC} − 50	mV
I_{IH}	Input HIGH Current (VTn Open)	−150		150	μA
I_{IL}	Input LOW Current (VTn Open)	−150		150	μA
CONTROL INPUT (SEL)					
V_{IH}	Input HIGH Voltage	V_{CC} x 0.65		V_{CC}	mV
V_{IL}	Input LOW Voltage	GND		V_{CC} x 0.35	mV
I_{IH}	Input HIGH Current	−150		+150	μA
I_{IL}	Input LOW Current	−200		+200	μA
TERMINATION RESISTORS					
R_{TIN}	Internal Input Termination Resistor	45	50	55	Ω
R_{TOUT}	Internal Output Termination Resistor	45	50	55	Ω

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. Input and output parameters vary 1:1 with V_{CC}.
6. CML outputs loaded with 50 Ω to V_{CC} for proper operation.
7. Vth, V_{IH}, V_{IL} and V_{ISE} parameters must be complied with simultaneously.
8. Vth is applied to the complementary input when operating in single−ended mode.
9. V_{IHD}, V_{ILD}, V_{ID} and V_{CMR} parameters must be complied with simultaneously.
10. V_{CMR} min varies 1:1 with GND, V_{CMR} max varies 1:1 with V_{CC}. The V_{CMR} range is referenced to the most positive side of the differential input signal.

Table 6. AC CHARACTERISTICS (V_{CC} = 1.71 V to 3.6 V; GND = 0 V; T_A = −40°C to 85°C) (Note 11)

Symbol	Characteristic		Min	Typ	Max	Unit
f_{MAX}	Maximum Input Clock Frequency	Voutpp ≥ 200 mV	7	8		GHz
$f_{DATAMAX}$	Maximum Operating Data Rate (PRBS23)		10.7	12		Gbps
fSEL	Maximum Toggle Frequency, SEL		25	50		MHz
V_{OUTPP}	Output Voltage Amplitude (@ $V_{INPPmin}$) (Note 12) (Figures 8 & 10)	f_{in} ≤ 7 GHz	200	400		mV
t_{PLH}, t_{PHL}	Propagation Delay to Differential Outputs, @ 1 GHz, measured at differential cross−point	INn/$\overline{INn}$ to Q, $\overline{Q}$ SEL to Q, $\overline{Q}$	120 5	180 13	240 22	ps ns
t_{PLH} TC	Propagation Delay Temperature Coefficient			50		Δfs/°C
t_{skew}	Device − Device skew (tpdmax − tpdmin)				50	ps
t_{DC}	Output Clock Duty Cycle (Reference Duty Cycle = 50%)	f_{in} ≤ 5.0 GHz f_{in} ≤ 7.0 GHz	45 40	50 50	55 60	%
t_{JITTER}	RJ − Output Random Jitter (Note 13) DJ − Residual Output Deterministic Jitter (Note 14)	f_{in} ≤ 7.0 GHz f_{in} ≤ 10.7 Gbps		0.2	0.8 10	ps RMS ps pk−pk
Φ_N	Phase Noise, f_c = 1 GHz	10 kHz 100 kHz 1 MHz 10 MHz 20 MHz 40 MHz		−135 −136 −150 −151 −151 −151		dBc
$t\int_{\Phi N}$	Integrated Phase Jitter (Figure 4) f_c = 1 GHz, 12 kHz − 20 MHz Offset (RMS)			35		fs
	Crosstalk Induced Jitter (Adjacent Channel) (Note 15)				0.7	ps RMS
V_{INPP}	Input Voltage Swing (Differential Configuration) (Figure 10) (Note 16)		100		1200	mV
t_r, t_f	Output Rise/Fall Times @ 1 GHz (20% − 80%)	Q, $\overline{Q}$	15	35	50	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

11. Measured using a V_{INPP}min source, 50% duty cycle clock source. All output loading with external 50 Ω to V_{CC}. Input edge rates 40 ps (20% − 80%).
12. Output voltage swing is a single−ended measurement operating in differential mode.
13. Additive RMS jitter with 50% duty cycle clock signal.
14. Additive Peak−to−Peak data dependent jitter with input NRZ data at PRBS23 at 3 Gbps.
15. Crosstalk is measured at the output while applying two similar clock frequencies that are asynchronous with respect to each other at the inputs.
16. Input voltage swing is a single−ended measurement operating in differential mode.

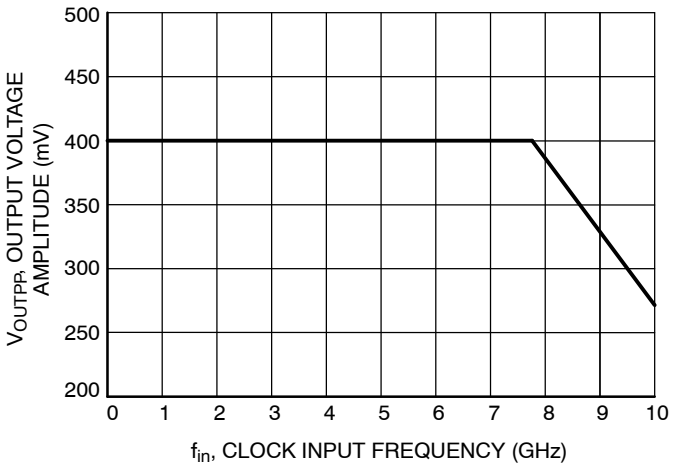


Figure 3. Output Voltage Amplitude (V_{OUTPP}) vs. Input Frequency (f_{in}) at Ambient Temperature (Typical)

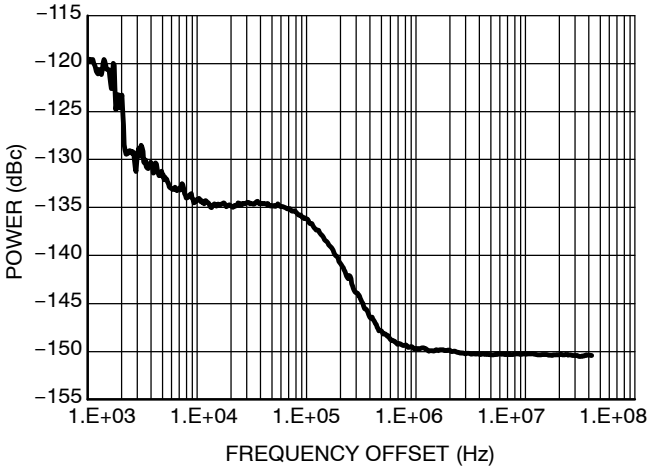


Figure 4. Typical Phase Noise (V_{CC} = 1.8 V, T = 25°C, f_c = 1 GHz)

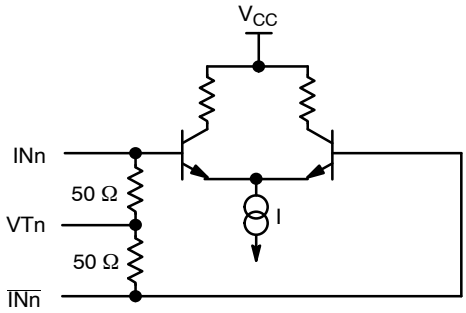


Figure 5. Input Structure

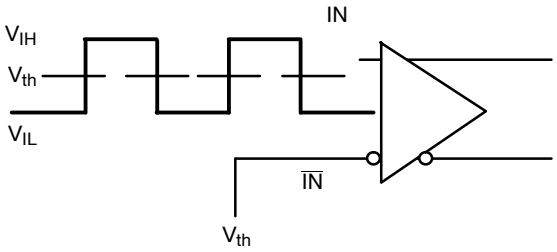


Figure 6. Differential Input Driven Single−Ended

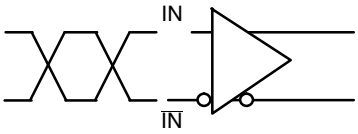


Figure 7. Differential Inputs Driven Differentially

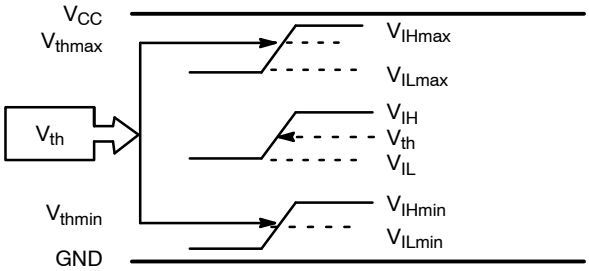


Figure 8. V_{th} Diagram

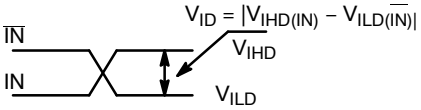


Figure 9. VID − Differential Inputs Driven Differentially

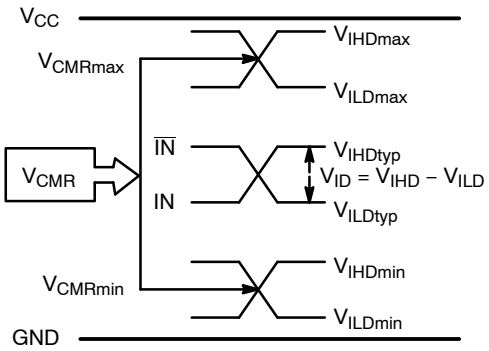


Figure 10. V_{CMR} Diagram

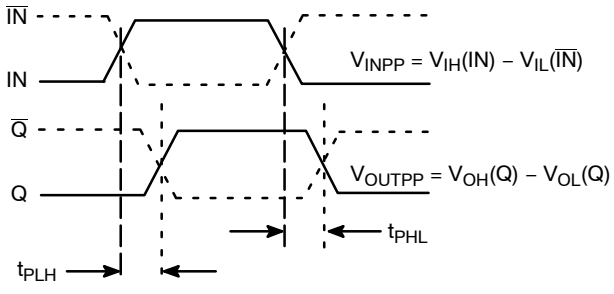


Figure 11. AC Reference Measurement

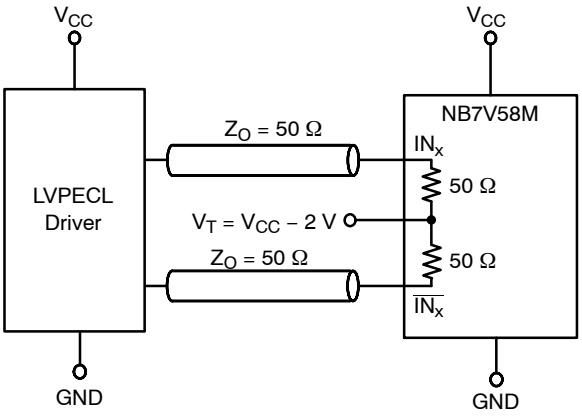


Figure 12. LVPECL Interface

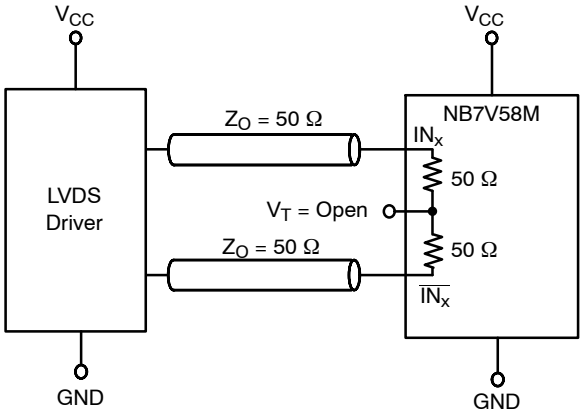


Figure 13. LVDS Interface

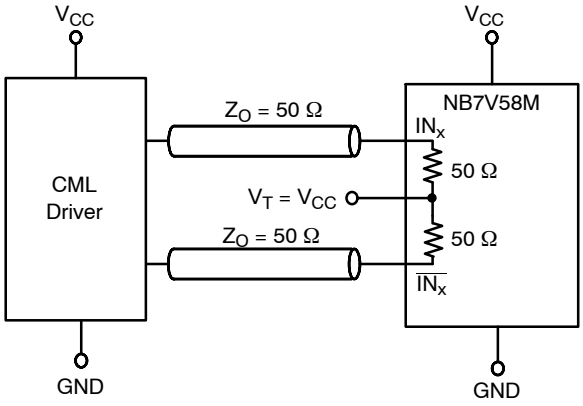


Figure 14. Standard 50 Ω Load CML Interface

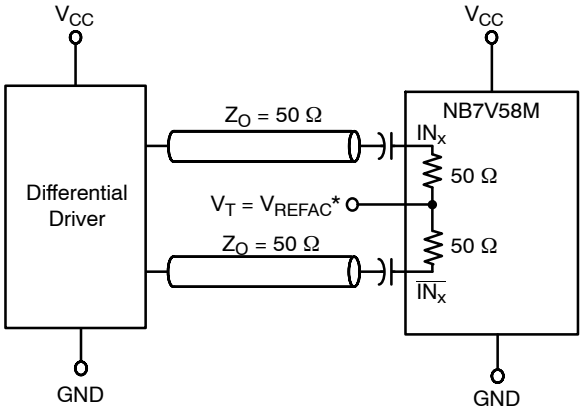


Figure 15. Capacitor−Coupled Differential Interface (V_T Connected to External V_{REFAC})

*V_{REFAC} Bypassed to Ground with 0.01 μF Capacitor

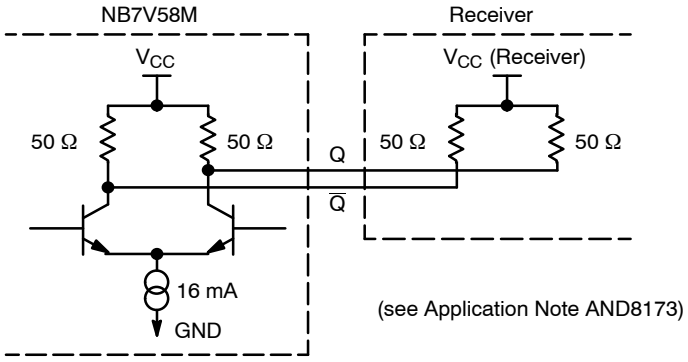


Figure 16. Typical CML Output Structure and Termination

ORDERING INFORMATION

Device	Package	Shipping†
NB7V58MMNG	QFN−16 (Pb−Free)	123 Units / Rail
NB7V58MMNHTBG	QFN−16 (Pb−Free)	100 / Tape & Reel
NB7V58MMNTXG	QFN−16 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

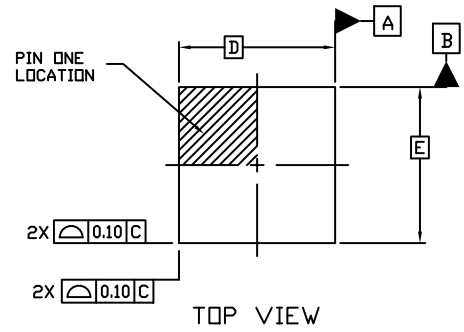
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MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

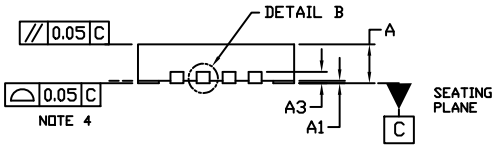
QFN16 3x3, 0.5P
CASE 485G
ISSUE G

DATE 08 OCT 2021

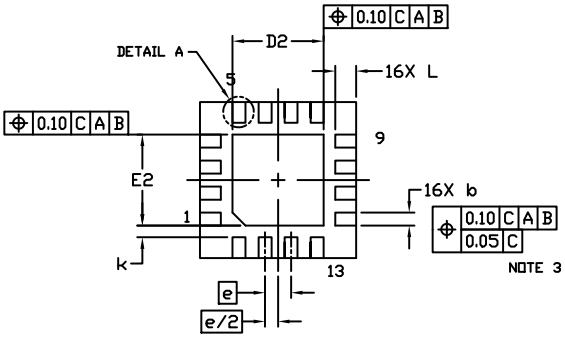
SCALE 2:1



TOP VIEW

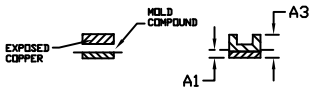


SIDE VIEW

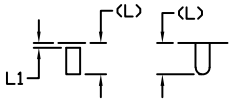


BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.



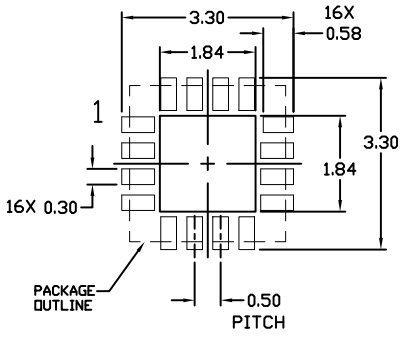
DETAIL B
ALTERNATE CONSTRUCTIONS



DETAIL A
ALTERNATE TERMINAL CONSTRUCTIONS

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.03	0.05
A3		0.20 REF	
b	0.18	0.24	0.30
D		3.00 BSC	
D2	1.65	1.75	1.85
E		3.00 BSC	
E2	1.65	1.75	1.85
e		0.50 BSC	
k		0.18 TYP	
L	0.30	0.40	0.50
L1	0.00	0.08	0.15

MOUNTING FOOTPRINT



GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**QFN16 3X3, 0.5P**	**PAGE 1 OF 1**

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